

IN THE CLAIMS:

Please note that all claims currently pending and under consideration in the referenced application are shown below. This listing of claims will replace all prior versions and listings of claims in the application. No claims have been amended herein

Listing of Claims:

1-18. (Canceled)

19. (Previously Presented) A method of fabricating a multi-die assembly, comprising:
providing a substrate including a plurality of conductors;
attaching at least one active face-down base die to the substrate in electrical communication with
at least some of the plurality of conductors;
providing a layer of electrically conductive epoxy adhesive to a back side of the at least one base
die;
placing a back side of at least one active face-up stack die on the layer of electrically conductive
epoxy adhesive;
curing the layer of electrically conductive epoxy adhesive and securing the back side of at least
one stack die to the at least one base die;
providing a direct electrical path between the at least one stack die and at least one of the
plurality of conductors; and
electrically grounding the at least one base die via the layer of electrically conductive epoxy
adhesive and the at least one stack die.

20. (Canceled)

21. (Previously Presented) The method of claim 19, further comprising:
securing at least one discrete component to at least one of the at least one stack die, the at least
one base die, and the substrate;

electrically connecting the at least one discrete component to at least one of the base die and the substrate; and
extending a die-to-component bond wire between the at least one stack die and the at least one discrete component.

22. (Previously Presented) The method of claim 21, further comprising:
extending a component-to-substrate bond wire between the at least one discrete component and at least one of the plurality of substrate conductors.

23. (Previously Presented) The method of claim 19, further comprising:
securing at least another stack die to the assembly; and
electrically connecting the at least another stack die and at least one of the plurality of substrate conductors.

24. (Canceled)

25. (Previously Presented) The method of claim 23, further comprising securing the at least another stack die to the at least one stack die.

26. (Previously Presented) The method of claim 25, further comprising:
securing at least one discrete component to the at least one stack die; and
extending a die-to-component bond wire between the at least another stack die and the at least one discrete component.

27. (Previously Presented) The method of claim 25, further comprising:
securing at least one discrete component to the at least one stack die; and
extending a component-to-substrate bond wire between the at least one discrete component and at least one of the plurality of substrate conductors.

28. (Previously Presented) The method of claim 25, further comprising:
securing at least one discrete component to the at least one base die; and
extending a die-to-component bond wire between the at least another stack die and the at least one discrete component.

29. (Previously Presented) The method of claim 25, further comprising:
securing at least one discrete component to the at least one base die; and
extending a component-to-substrate bond wire between the at least one discrete component and at least one of the plurality of substrate conductors.

30. (Previously Presented) The method of claim 19, wherein the attaching at least one active face-down base die includes attaching at least two active face-down base die to the substrate and electrically coupling each of the at least two base die with at least one of the plurality of substrate conductors.

31. (Previously Presented) The method of claim 30, further comprising bridging the at least one stack die between the at least two base die.

32. (Previously Presented) The method of claim 31, further comprising securing at least another stack die over the at least one stack die.

33. (Previously Presented) The method of claim 19, further comprising:
securing at least one discrete component to the substrate; and
extending a die-to-component bond wire between the at least one stack die and the at least one discrete component.

34. (Previously Presented) The method of claim 33, further comprising extending a die-to-component bond wire between the at least one discrete component and at least one of the plurality of substrate conductors.